AMENDMENTS TO THE CLAIMS

1-27. (Cancelled)

28. (Currently Amended) A method for inserting components to a board, comprising:

at a component grasping position, releasably grasping a first component, having a device portion and a lead wire at said device portion, by applying a first grasping pressure to the device portion of said first component;

while releasably grasping said first component, performing a first positional alignment in a direction along a surface of the board to align said lead wire of said first component and a first lead-wire insertion hole of said board;

after said performing of said first positional alignment, inserting said lead wire of said first component into said first lead-wire insertion hole of said board;

at said component grasping position, releasably grasping a second component, having a device portion and a lead wire at said device portion, by applying a second grasping pressure to the device portion of said second component;

while releasably grasping said second component, performing a second positional alignment in a direction along said surface of said board to align said lead wire of said second component and a second lead-wire insertion hole of said board;

after said performing of said second positional alignment, inserting said lead wire of said second component into said second lead-wire insertion hole of said board; and

for at least one of said first and second components, correcting an insertion posture of the component prior to said inserting of the lead wire of the component into the respective one of the first and second lead-wire insertion holes,

wherein said correcting of the insertion posture of the component includes grasping said lead wire of said component and performing positional alignment in a direction along a surface of the board between the lead wire of the component and the respective lead-wire insertion hole of the board, and grasping the device portion of the component whose lead wire is grasped so as to move the device portion in the direction along the surface of the board about a fulcrum defined at a grasped position of the lead wire to correct a bend of the lead wire such that the device portion is placed at a component insertion position,

wherein said device portion of said first component is lower in rigidity than said device portion of said second ~~component; and~~ component,

wherein said releasably grasping of said first component and said releasably grasping of said second component are carried out such that said first grasping pressure applied to said first component is lower than said second grasping pressure applied to said second component,

wherein said first and second grasping pressures are such that said releasably grasping of said first component and said releasably grasping of said second component are carried out without plastically deforming configurations of the device portions of said first and second components,

wherein said first and second components comprise radial components, respectively.

29-34. (Cancelled)

35. (Currently Amended) The component insertion method according to claim [[34]] 28, wherein

after the correction of the insertion posture of the component, an end portion of the lead wire of the component is held by a guide pin through the insertion hole of the board, and the grasping of the device portion and the grasping of the lead wire are released; and

the guide pin is moved so that the end portion of the lead wire is guided to the insertion hole of the board, thereby inserting the lead wire of the component into the insertion hole.

36. (Currently Amended) The component insertion method according to claim [[34]] 28, wherein

each of the components that are radial components has a plurality of the lead wires formed so as to be arrayed in one line, and

the correction of the insertion posture of the component is performed by moving the device portion in a direction extending along a surface of the board and generally perpendicular to the array direction of the lead wires.